

Dual P-Channel 20-V (D-S) MOSFET

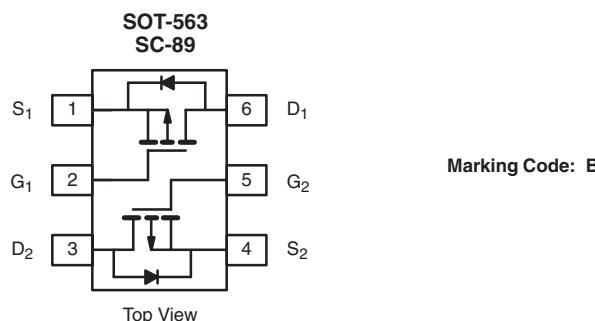
PRODUCT SUMMARY		
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (mA)
- 20	1.2 at V _{GS} = - 4.5 V	- 350
	1.6 at V _{GS} = - 2.5 V	- 300
	2.7 at V _{GS} = - 1.8 V	- 150

FEATURES

- Halogen-free Option Available
- TrenchFET® Power MOSFET: 1.8 V Rated
- Very Small Footprint
- High-Side Switching
- Low On-Resistance: 1.2 Ω
- Low Threshold: 0.8 V (typ.)
- Fast Switching Speed: 14 ns
- 1.8 V Operation
- Gate-Source ESD Protected: 2000 V



RoHS
COMPLIANT



Ordering Information: Si1023X-T1-E3 (Lead (Pb)-free)
Si1023X-T1-GE3 (Lead (Pb)-free and Halogen-free)

BENEFITS

- Ease in Driving Switches
- Low Offset (Error) Voltage
- Low-Voltage Operation
- High-Speed Circuits
- Low Battery Voltage Operation

APPLICATIONS

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pagers

ABSOLUTE MAXIMUM RATINGS T_A = 25 °C, unless otherwise noted

Parameter	Symbol	5 s	Steady State	Unit	
Drain-Source Voltage	V _{DS}	- 20	± 6	V	
Gate-Source Voltage	V _{GS}				
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 25 °C	I _D	- 390	mA	
	T _A = 85 °C		- 280		
Pulsed Drain Current ^b	I _{DM}	- 650			
Continuous Source Current (Diode Conduction) ^a	I _S	- 450	- 380		
Maximum Power Dissipation ^a	T _A = 25 °C	P _D	280	mW	
	T _A = 85 °C		145		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150		°C	
Gate-Source ESD Rating (HBM, Method 3015)	ESD	2000		V	

Notes:

a. Surface Mounted on FR4 board.

b. Pulse width limited by maximum junction temperature.

SPECIFICATIONS $T_J = 25^\circ\text{C}$, unless otherwise noted

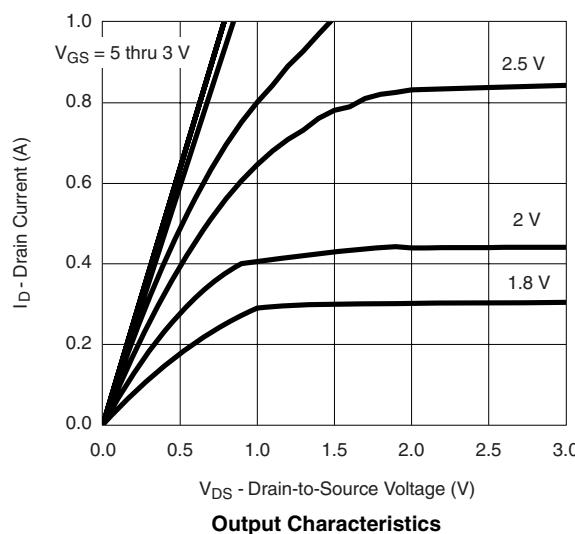
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = -250 \mu\text{A}$	- 0.45			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}$, $V_{GS} = \pm 4.5 \text{ V}$		± 1	± 2	μA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -16 \text{ V}$, $V_{GS} = 0 \text{ V}$		- 0.3	- 100	nA
		$V_{DS} = -16 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 85^\circ\text{C}$			- 5	μA
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} = -5 \text{ V}$, $V_{GS} = -4.5 \text{ V}$	- 700			mA
Drain-Source On-State Resistance ^a	$R_{DS(\text{on})}$	$V_{GS} = -4.5 \text{ V}$, $I_D = -350 \text{ mA}$		0.8	1.2	Ω
		$V_{GS} = -2.5 \text{ V}$, $I_D = -300 \text{ mA}$		1.2	1.6	
		$V_{GS} = -1.8 \text{ V}$, $I_D = -150 \text{ mA}$		1.8	2.7	
Forward Transconductance ^a	g_{fs}	$V_{DS} = -10 \text{ V}$, $I_D = -250 \text{ mA}$		0.4		S
Diode Forward Voltage ^a	V_{SD}	$I_S = -150 \text{ mA}$, $V_{GS} = 0 \text{ V}$		- 0.8	- 1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = -10 \text{ V}$, $V_{GS} = -4.5 \text{ V}$, $I_D = -250 \text{ mA}$		1500		pC
Gate-Source Charge	Q_{gs}			150		
Gate-Drain Charge	Q_{gd}			450		
Turn-On Time	$t_{d(\text{on})}$	$V_{DD} = -10 \text{ V}$, $R_L = 47 \Omega$ $I_D \equiv -200 \text{ mA}$, $V_{GEN} = -4.5 \text{ V}$, $R_G = 10 \Omega$		14		ns
Turn-Off Time	$t_{d(\text{off})}$			46		

Notes:

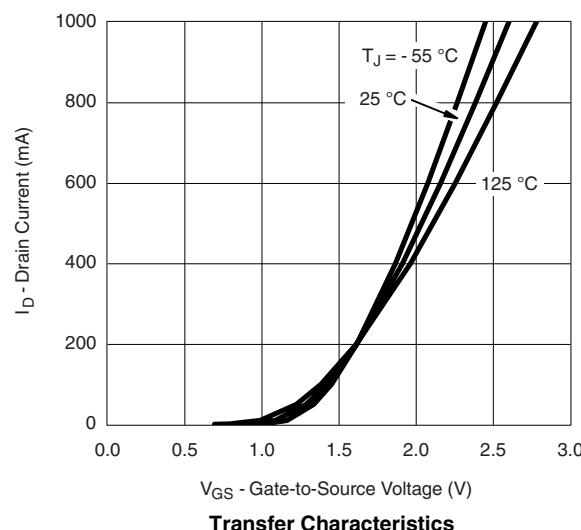
a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.

b. Guaranteed by design, not subject to production testing.

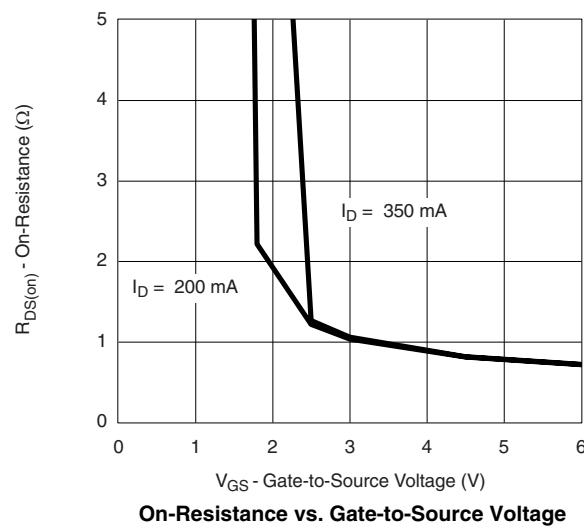
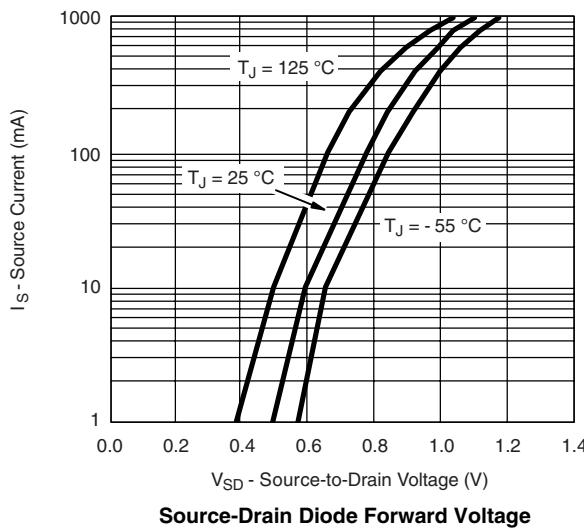
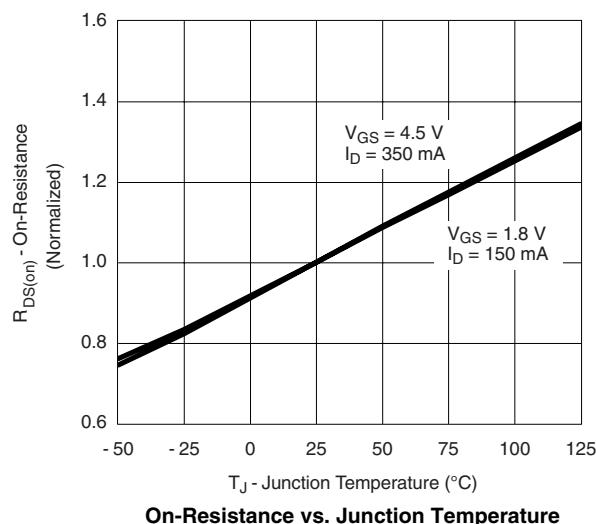
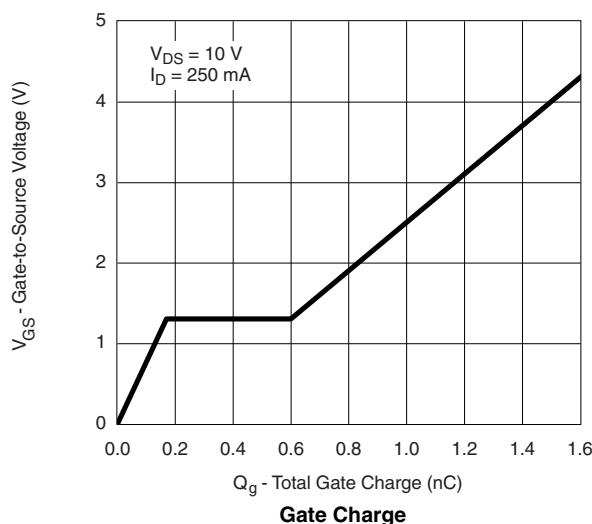
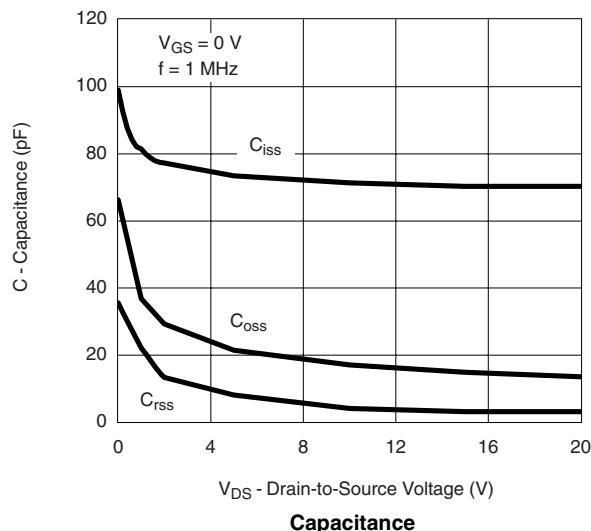
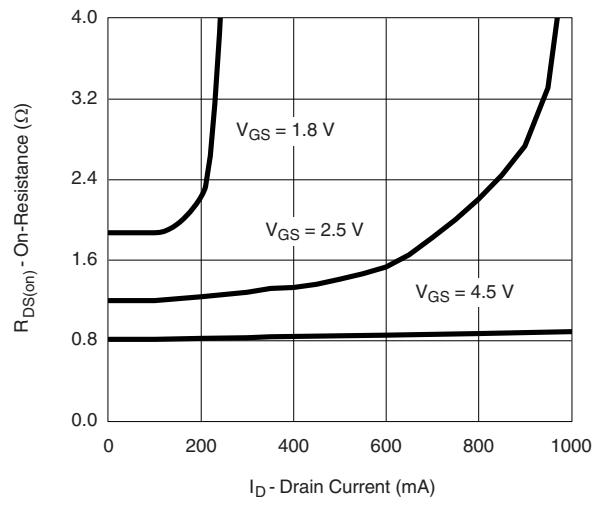
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

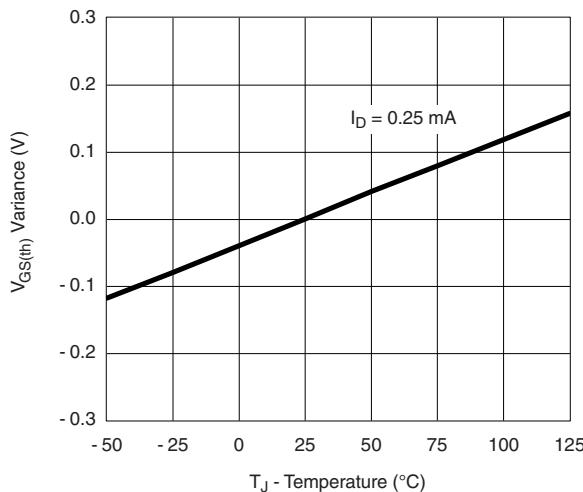
TYPICAL CHARACTERISTICS $T_A = 25^\circ\text{C}$, unless otherwise noted

Output Characteristics

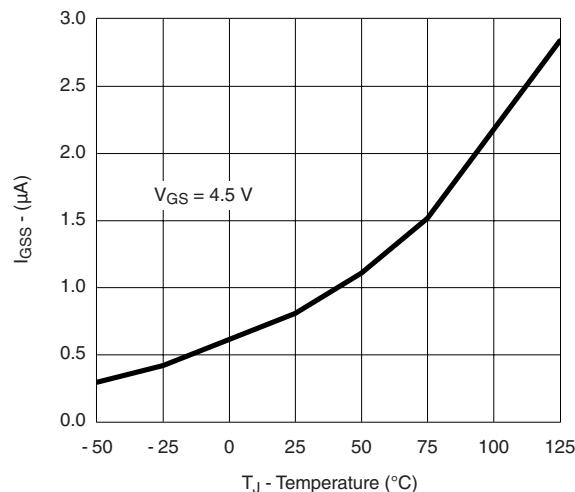
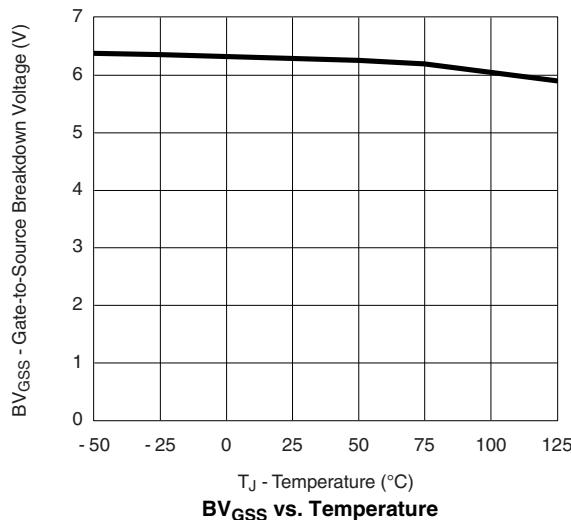
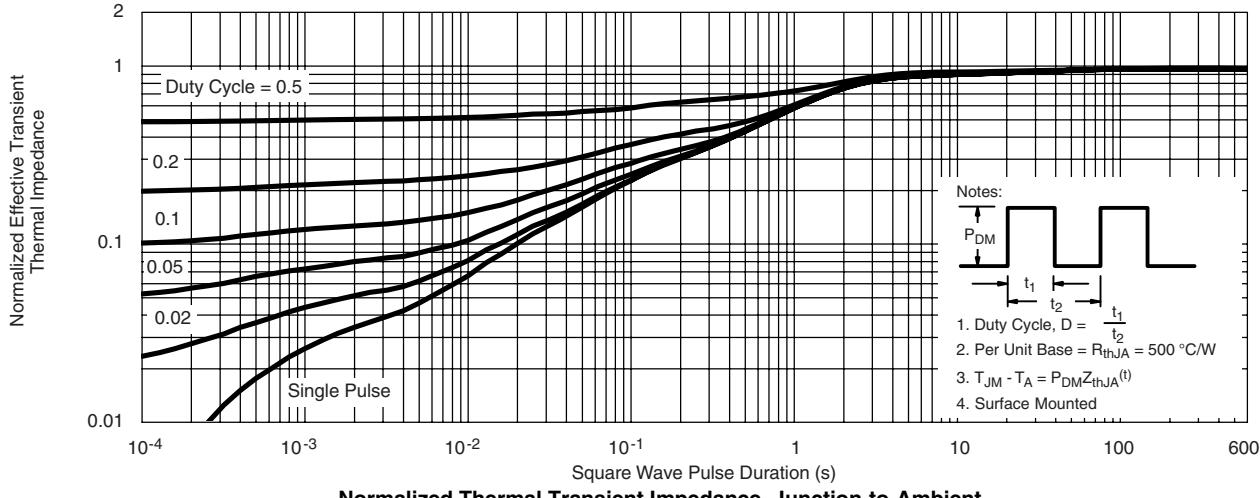


Transfer Characteristics

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Threshold Voltage Variance vs. Temperature

 I_{GSS} vs. Temperature BV_{GSS} vs. Temperature

Normalized Thermal Transient Impedance, Junction-to-Ambient

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